

Typical Applications

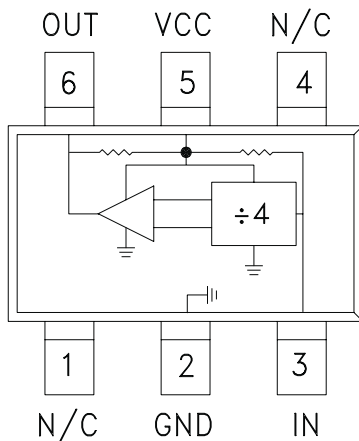
Prescaler for DC to C Band PLL Applications:

- UNII, Point-to-Point & VSAT Radios
- 802.11a & HiperLAN WLAN
- Fiber Optic
- Cellular / 3G Infrastructure

Features

- Ultra Low SSB Phase Noise: -150 dBc/Hz
- Single-Ended I/O's
- Output Power: -2 to -3.5 dBm
- Single DC Supply: +3V @ 53 mA
- 9 mm² Ultra Small Package: SOT26

Functional Diagram



General Description

The HMC433 & HMC433E are low noise Divide-by-4 Static Dividers utilizing InGaP GaAs HBT technology in ultra small surface mount SOT26 plastic packages. This device operates from DC (with a square wave input) to 8.0 GHz input frequency with a single +3.0V DC supply. Single-ended inputs and outputs reduce component count and cost. The low additive SSB phase noise of -150 dBc/Hz at 100 kHz offset helps the user maintain good system noise performance.

Electrical Specifications, $T_A = +25^\circ\text{C}$, 50 Ohm System, $V_{CC} = +3V$

| Parameter | Conditions | Min. | Typ. | Max. | Units |
|----------------------------------|----------------------------------------------------------|------|------|------|--------|
| Maximum Input Frequency | | 8 | 8.5 | | GHz |
| Minimum Input Frequency | Sine Wave Input. [1] | | 0.2 | | GHz |
| Input Power Range | $F_{in} = 1$ to 6 GHz | -12 | -15 | +12 | dBm |
| | $F_{in} = 6$ to 8 GHz | -3 | -7 | +10 | dBm |
| Output Power | $F_{in} = 4$ GHz | -5.0 | -2.0 | | dBm |
| | $F_{in} = 8$ GHz | -6.5 | -3.5 | | dBm |
| Reverse Leakage | RF Output Terminated, $F_{in} = 4$ GHz, $P_{in} = 0$ dBm | | -25 | | dBm |
| SSB Phase Noise (100 kHz offset) | $P_{in} = 0$ dBm, $F_{in} = 4$ GHz | | -150 | | dBc/Hz |
| Output Transition Time | $P_{in} = 0$ dBm, $F_{out} = 882$ MHz | | 120 | | ps |
| Supply Current (I_{CC}) | $V_{CC} = +3.0V$ | | 53 | | mA |

1. Divider will operate down to DC for square-wave input signal.



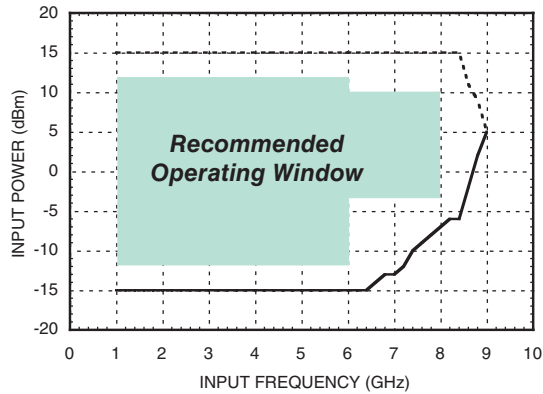
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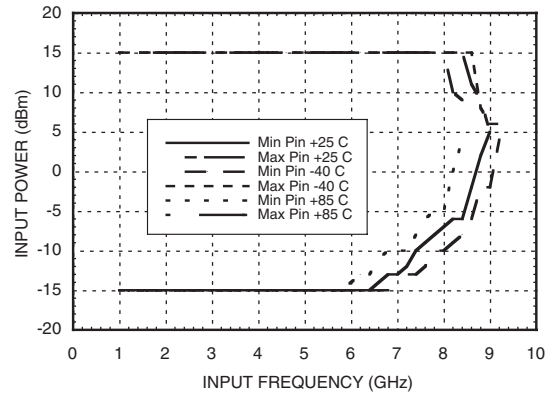
HMC433 / 433E

SMT GaAs HBT MMIC DIVIDE-BY-4, DC - 8.0 GHz

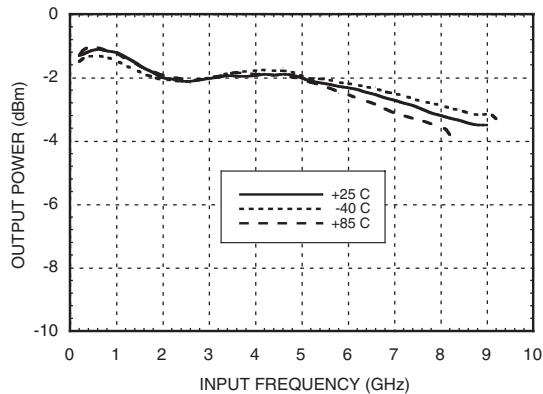
Input Sensitivity Window, T= 25 °C



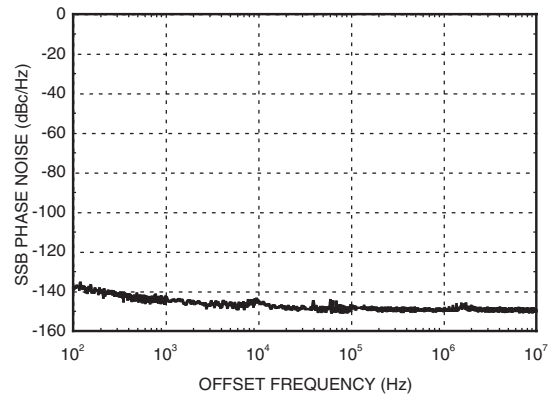
Input Sensitivity Window vs. Temperature



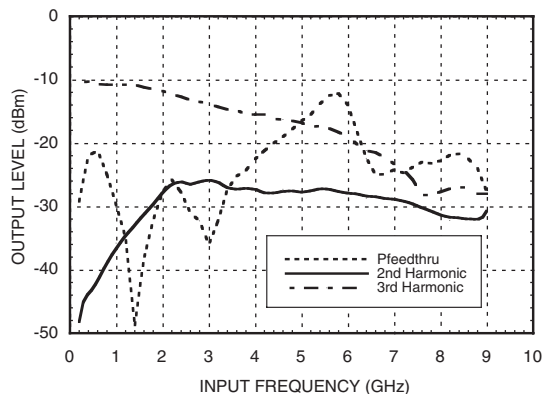
Output Power vs. Temperature



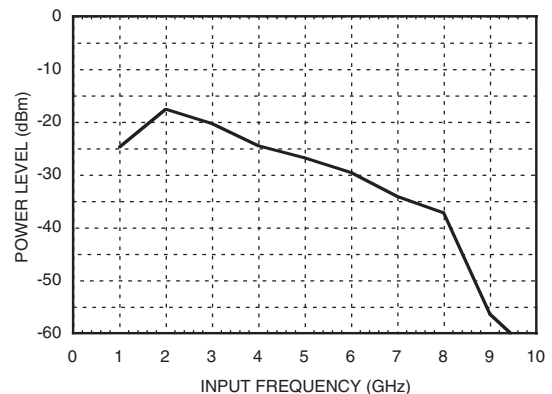
SSB Phase Noise Performance, Pin= 0 dBm, T= 25 °C



Output Harmonic Content, Pin= 0 dBm, T= 25 °C



Reverse Leakage, Pin= 0 dBm, T= 25 °C





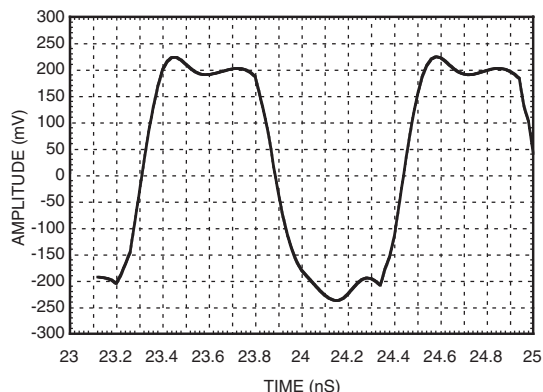
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HMC433 / 433E

SMT GaAs HBT MMIC DIVIDE-BY-4, DC - 8.0 GHz

Output Voltage Waveform,
Pin= 0 dBm, Fout= 882 MHz, T= 25 °C



Absolute Maximum Ratings

| | |
|-----------------------------------------------------------------------|----------------|
| RF Input (Vcc= +3.0V) | +15 dBm |
| Vcc | +3.5V |
| Maximum Channel Temperature | 135 °C |
| Continuous P _{diss} (T=85 °C) (derate 5mW/°C above 85 °C) | 250mW |
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -40 to +85 °C |
| ESD Sensitivity (HBM) | Class 1A |

DC blocking capacitors are required at RF input and RF output ports. Choose value for lowest frequency of operation.



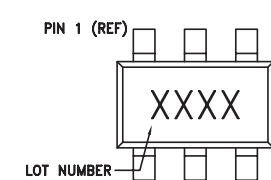
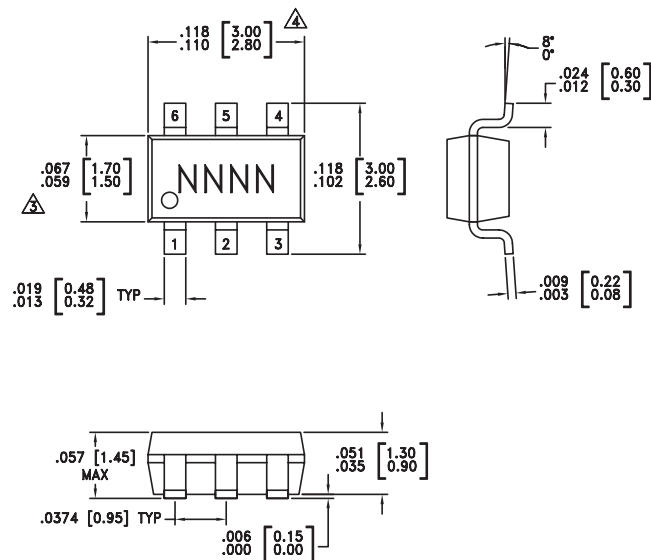
**ELECTROSTATIC SENSITIVE DEVICE
OBSERVE HANDLING PRECAUTIONS**

Typical Supply Current vs. Vcc

| Vcc (V) | Icc (mA) |
|---------|----------|
| 2.70 | 42 |
| 3.0 | 53 |
| 3.30 | 63 |

Note: Divider will operate over full voltage range shown above

Outline Drawing



- NOTES:
- LEADFRAME MATERIAL: COPPER ALLOY
 - DIMENSIONS ARE IN INCHES [MILLIMETERS]
 - LEAD SPACING TOLERANCE IS NON-CUMULATIVE.
 - PAD BURR LENGTH SHALL BE 0.15mm MAXIMUM.
PAD BURR HEIGHT SHALL BE 0.05mm MAXIMUM.
 - PACKAGE WARP SHALL NOT EXCEED 0.05mm.
 - ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
 - REFER TO HITTITE APPLICATION NOTE FOR SUGGESTED LAND PATTERN.

Package Information


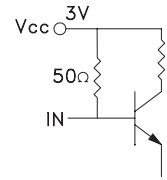
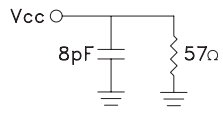
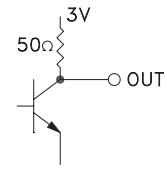
| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking ^[3] |
|-------------|----------------------------------------------------|---------------|---------------------|--------------------------------|
| HMC433 | Low Stress Injection Molded Plastic | Sn/Pb Solder | MSL1 ^[1] | H433 XXXX |
| HMC433E | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 ^[2] | 433E XXXX |

[1] Max peak reflow temperature of 235 °C

[2] Max peak reflow temperature of 260 °C

[3] 4-Digit lot number XXXX

Pin Description

| Pin Number | Function | Description | Interface Schematic |
|------------|----------|------------------------------------|---------------------------------------------------------------------------------------|
| 1, 4 | N/C | No Connection | |
| 2 | GND | Pin must connect to RF/DC ground. |  |
| 3 | IN | RF input must be DC blocked. |  |
| 5 | Vcc | Supply voltage 3V ± 0.3V. |  |
| 6 | OUT | Divided output must be DC blocked. |  |



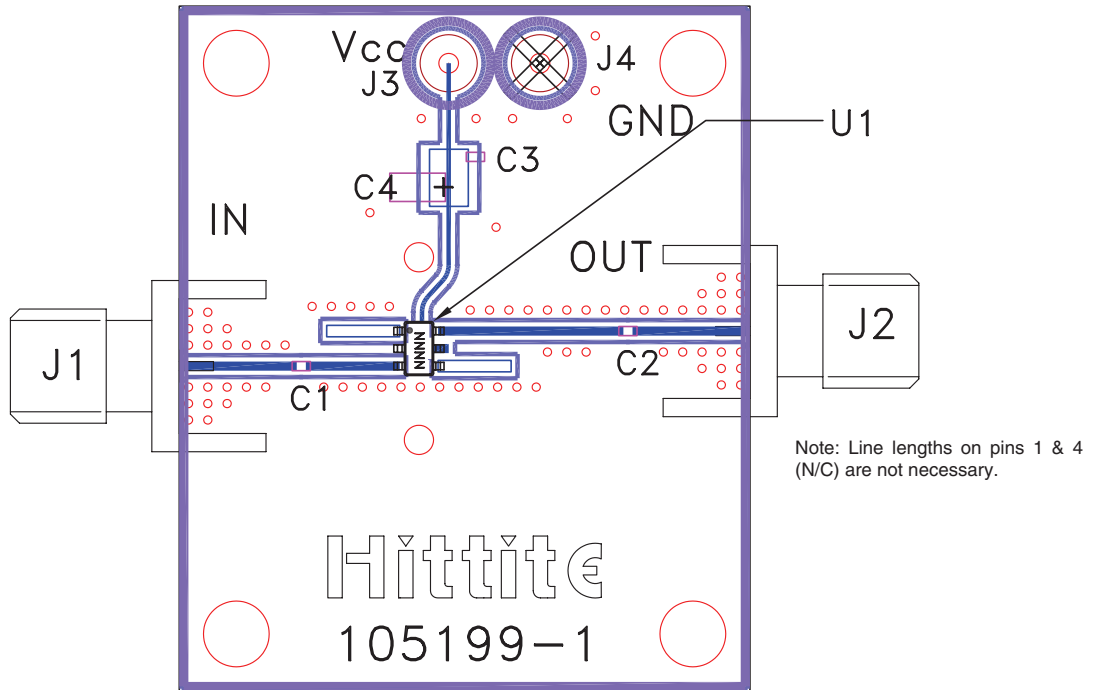
MICROWAVE CORPORATION v02.0705



HMC433 / 433E

SMT GaAs HBT MMIC DIVIDE-BY-4, DC - 8.0 GHz

Evaluation PCB



List of Materials for Evaluation PCB 105675 [1]

| Item | Description |
|---------|------------------------------------------|
| J1 - J2 | PCB Mount SMA RF Connector |
| J3 - J4 | DC Pin |
| C1 - C2 | 100 pF Capacitor, 0402 Pkg. |
| C3 | 1000 pF Capacitor, 0402 Pkg. |
| C4 | 10 μ F Tantalum Capacitor, 1206 Pkg. |
| U1 | HMC433 / HMC433E Divide-by-4 |
| PCB [2] | 105199 Eval Board |

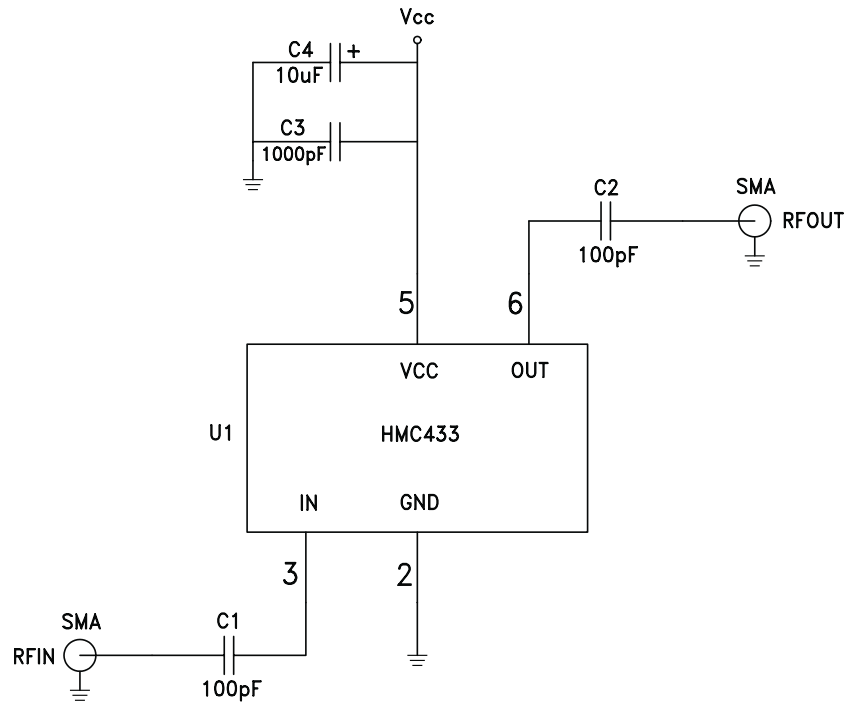
[1] Reference this number when ordering complete evaluation PCB

[2] Circuit Board Material: Rogers 4350

The circuit board used in the final application should use RF circuit design techniques. Signal lines should have 50 ohm impedance while the package ground leads should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation circuit board shown is available from Hittite upon request.



Application Circuit



Note:

DC blocking capacitor values (C1, C2) and DC decoupling capacitor values (C3, C4) are chosen for lowest frequency of operation.